

AIXTRON

Q3/2026 Investor Presentation

Dr. Felix Grawert, CEO
Dr. Christian Danninger, CFO
October 29th, 2026

Forward-Looking Statements

This document may contain forward-looking statements regarding the business, results of operations, financial condition and earnings outlook of AIXTRON. These statements may be identified by words such as “may”, “will”, “expect”, “anticipate”, “contemplate”, “intend”, “plan”, “believe”, “continue” and “estimate” and variations of such words or similar expressions. These forward-looking statements are based on the current assessments, expectations and assumptions of the executive board of AIXTRON, of which many are beyond control of AIXTRON, based on information available at the date hereof and subject to risks and uncertainties. You should not place undue reliance on these forward-looking statements. Should these risks or uncertainties materialize or should underlying expectations not occur or assumptions prove incorrect, actual results, performance or achievements of AIXTRON may materially vary from those described explicitly or implicitly in the relevant forward-looking statement. This could result from a variety of factors, such as those discussed by AIXTRON in public reports and statements, including but not limited to those reported in the chapter “Risk Report”. AIXTRON undertakes no obligation to revise or update any forward-looking statements as a result of new information, future events or otherwise, unless expressly required to do so by law.

Due to rounding, numbers presented throughout this report may not add up precisely to the totals indicated and percentages may not precisely reflect the absolute figures for the same reason.

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Q3/2026 Key highlights

Q3/2026 results: Strong AI-driven optoelectronics demand accelerating ahead of expectations

- Order Intake of EUR 275m, driven by exceptionally strong demand for AI-related photonics applications (Q3/2025: EUR 124m)
- Revenues of EUR 184m reflecting ramp of photonics business
- Gross Profit at EUR 87m; Gross Margin at 48% due to better product and regional mix
- EBIT at EUR 57m; EBIT Margin at 31%

Strong cash generation

- Free cash flow of EUR 290m in 9M/26, up EUR 180m yoy, mainly driven by higher customer advance payments
- Net financial assets increased to EUR 591m, supported by strong free cash flow and the net effect of the convertible bond

Production ramp fully on track

- Output increased significantly in every quarter of 2026
- Further output increase targeted for Q4
- Strong order backlog supports FY/2026 guidance

FY/2026 guidance[1] confirmed

- Revenues FY/26E: EUR 560m ± 30m
- Gross Margin FY/26E: around 42%
- EBIT Margin FY/26E: 17% – 20%

} incl. mid-single-digit EUR million expense for personnel reduction in operations area in Q1

Outlook 2027

- Significant growth expected in 2027, led by optoelectronics and supported by increasing momentum in power electronics

1 FY/26 Based on $1.20/€ Budget Rate

Q3/2026 Market & business development

Optoelectronics

- 68% of Q3/2026 equipment order intake
- Global demand from US, Europe, China, Japan, Taiwan and Singapore
- AI networking drives investments in transceivers and InP manufacturing
- Demand exceeds original market expectations and backlog provides visibility well into 2027

GaN

- Low-voltage AI power applications progressing through development and qualification (800V HVDC power)
- Inquiries and orders from selected high-volume customers starting
- Broad market demand expected to kick in once low-voltage adoption becomes broader

SiC

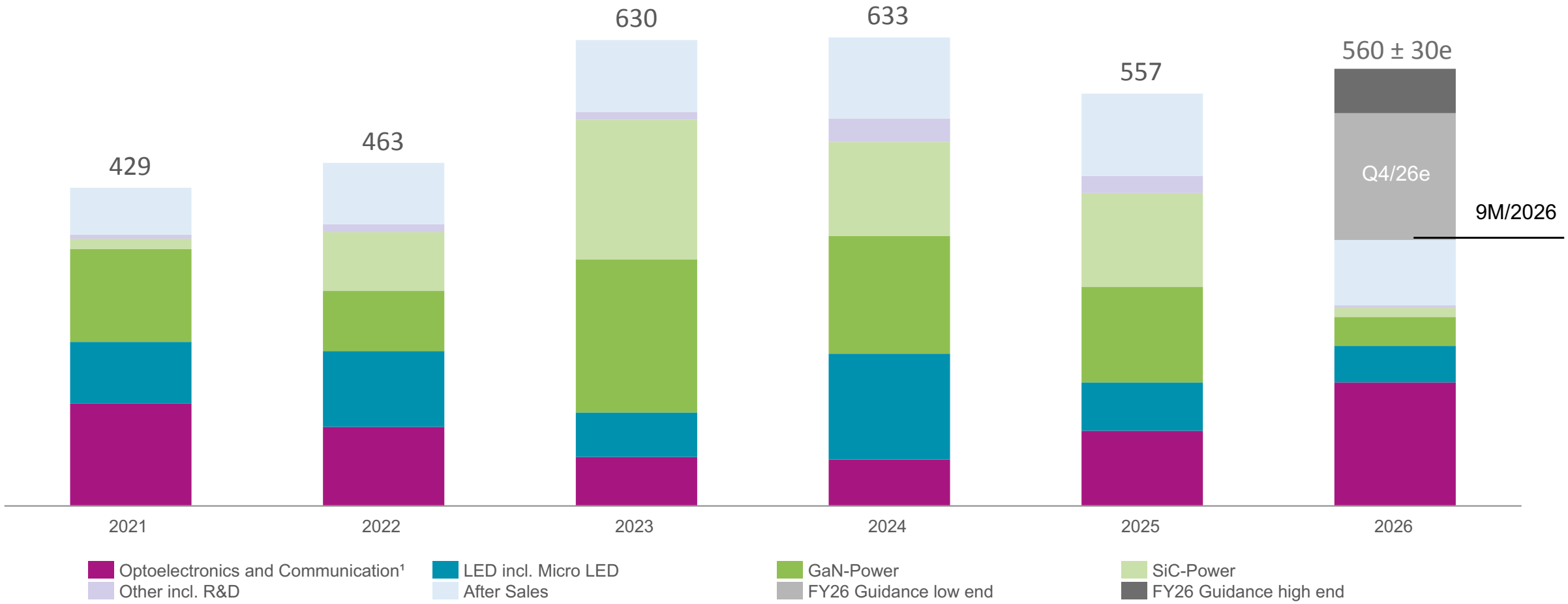
- Additional demand driven by AI / industrial applications, i.e., from higher voltage class devices
- Customer utilization and consumables consumption improving
- First new orders for 200 mm capacity expansions

LED / Micro LED

- Demand remains soft
- AR and AI optical interconnect activity increasing
- Long-term opportunity remains attractive

Annual Revenues by Application

EUR million



1 Includes applications in Consumer Optoelectronics, Solar and Telecom/Datacom

9M/2026 – Highlights | Key P&L Indicators

	Revenues	Gross Profit	Margin	EBIT	Margin
Q3/26	EUR 184m *+54% YoY*	EUR 87m *+88% YoY*	*48%*	EUR 57m *+268% YoY*	*31%*
9M/26	EUR 358m *-3% YoY*	EUR 145m *+6% YoY*	*40%*	EUR 49m *+16% YoY*	*14%*

- Q3 revenue increased by 54% yoy, reflecting the high demand especially in optoelectronics
- Gross margin increased to 48%, driven by higher revenue and a favorable product and regional mix
- EBIT margin increased to 31%, supported by the higher gross margin and operating leverage
- 9M operating expenses were slightly higher year-on-year, mainly due to a 17% increase in R&D expenses

9M/2026 – Highlights | Key Balance Sheet & Cash Flow Indicators

	Working Capital[1]	Operating Cash Flow	Free Cash Flow	Net Financial Assets[2]
Q3/26	EUR 84m *EUR -68m vs. Q2/26*	EUR 138m *EUR +95m YoY*	EUR 128m *EUR +89m YoY*	EUR 591m *EUR +124m vs. Q2/26*
9M/26	EUR 84m *EUR -254m vs. Q4/25*	EUR 311m *EUR +183m YoY*	EUR 290m *EUR +180m YoY*	EUR 591m *EUR +366m vs. Q4/25*

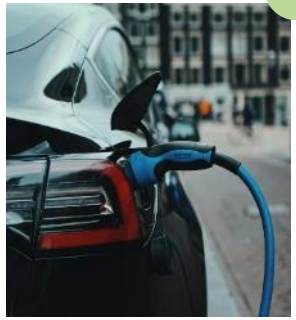
- Strong operating cash flow primarily driven by higher customer advance payments
- Advance payments reflect the order backlog, order composition and individual payment terms
- Customer prepayments support the upcoming production ramp
- Increase in net financial assets driven by EUR 290m free cash flow and the net effect of the convertible bond, partly offset by the EUR 17m dividend payment

1 Working Capital = Inventories + Trade Receivables - Trade Payables - Contract Liabilities for Advance Payments; FX-effects excluded in illustrated Change in Working Capital
2 Including other current financial assets minus financial liability of convertible bond

We address a comprehensive set of growth applications with our G10 family of products

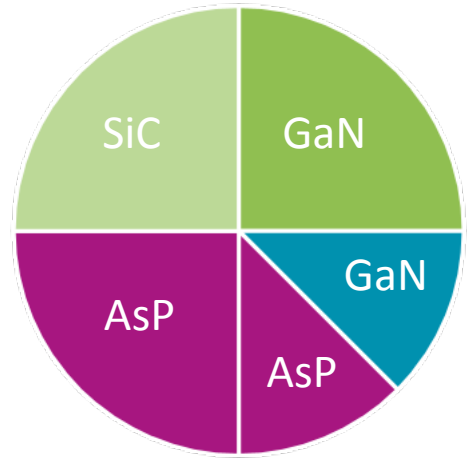
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Power Electronics



SiC Power

- EV main inverters and EV OBCs
- EV charging infrastructure
- Data centers: AC/DC
- Wind & PV
- Traction & large drives



GaN Power & RF

- Fast charging / mobile devices
- Data centers: AC/DC & DC/DC
- Motor drives, e.g. white goods
- AI power delivery
- EV OBCs
- Base stations



Optoelectronics / LEDs



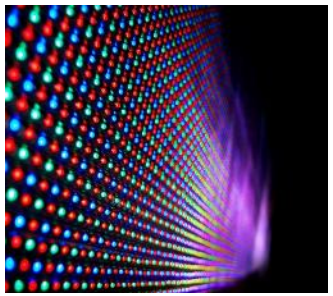


Lasers

- Optical data communication
- 3D sensing
- LiDAR
- Industrial power lasers

Micro LEDs / Specialty LEDs

- Industrial displays (in/outdoor)
- TVs
- Smart watches / AR glasses
- Automotive
- Horticulture



Optoelectronics – momentum in laser market continues to be strong



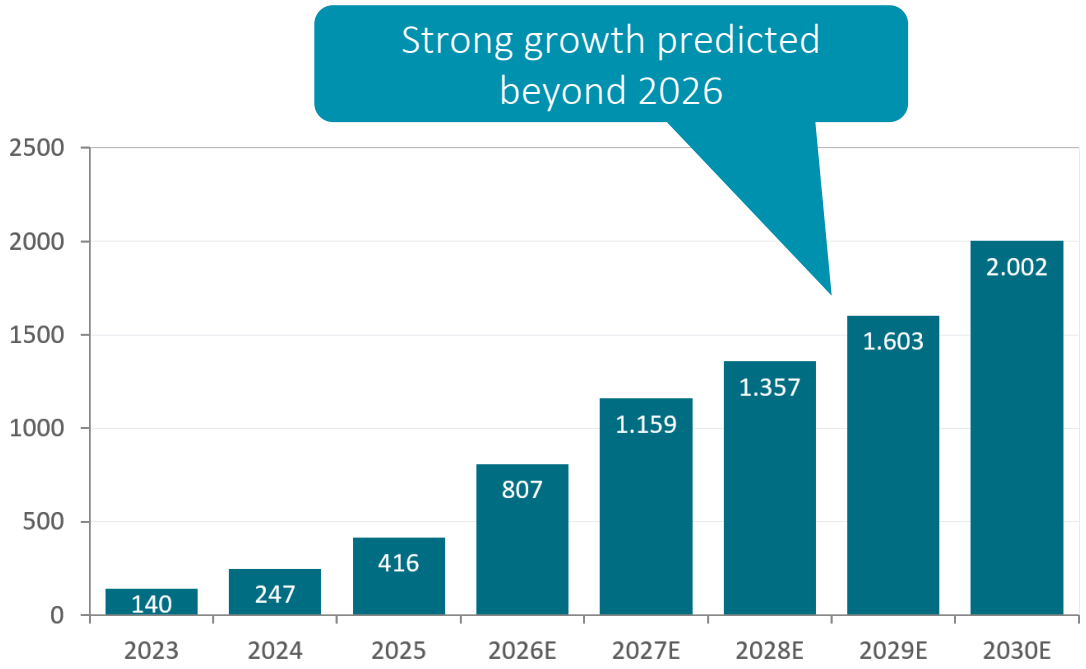
G10-AsP:
Tool of record

G10-AsP Platform: Securing top-tier engagements

- **G10 AsP** recognized as **tool of record by leading customers** – further engagements progressing with additional prospects.
- Demand for InP-based edge-emitting lasers remained robust, driven by **AI** and **datacenter applications**
- **PIC applications driving of orders**:
  - Multiple photonic components are integrated on a single chip, enabling **faster, energy-efficient data transmission** using light.
  - Applications: **AI, data center, 5G, LiDAR and quantum computing.**
- **G10-AsP tool of record** for the photonics ramp:
  - "In-situ clean" is ideally suited to multi-step processes of these devices
  - Flexible use for 75/ 100/ 150/ 200mm wafer size(s)

AI data centers are accelerating the transition from copper to optical interconnects
The current demand cycle remains at an early stage and is expected to extend until 2030

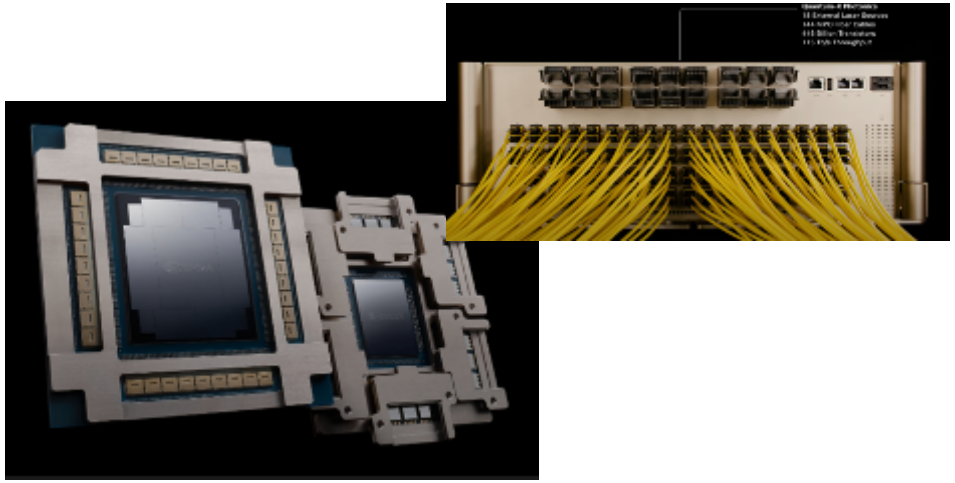
Hyperscaler AI CapEx 2023–2030E (USD Billions, estimated)



Source: ODDO BHF Securities, AI Capex note, Oct 2026

Optical Interconnects replace Cu wiring in Datacenter

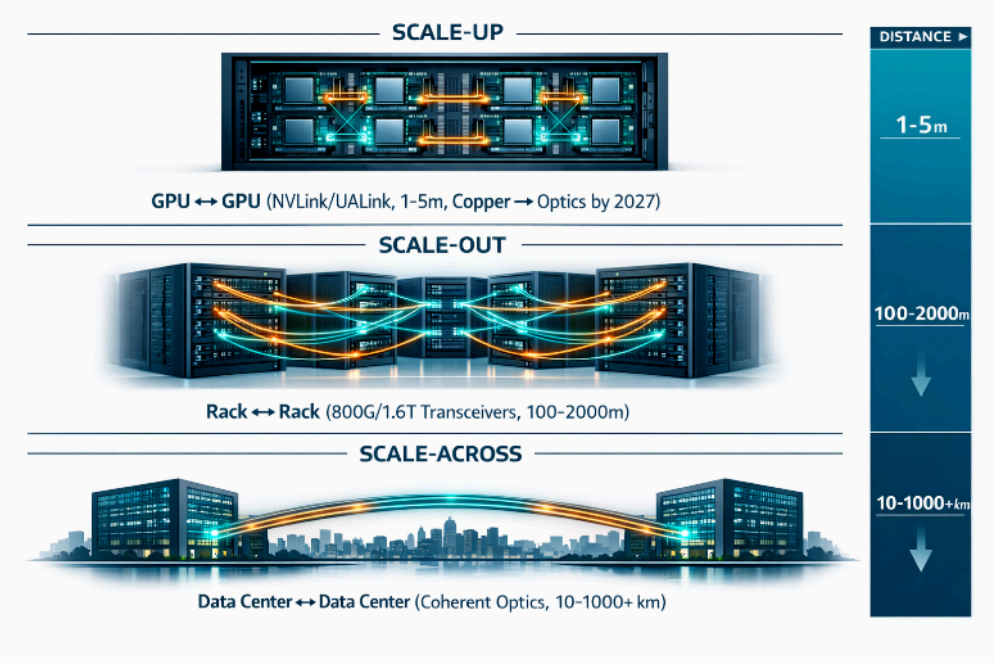
- Modern AI GPU clusters (NVIDIA Blackwell GB200 NVL72 and beyond) demand high optical interconnect bandwidth.
- Each rack needs thousands of high-speed optical links.



AI infrastructure is the #1 demand driver for everything downstream: compute, networking, optics, lasers, and epitaxy equipment.

Hyperscaler capex has quadrupled since GPT-4's release | Epoch AI

Demand in the InP datacom market is growing rapidly across three areas



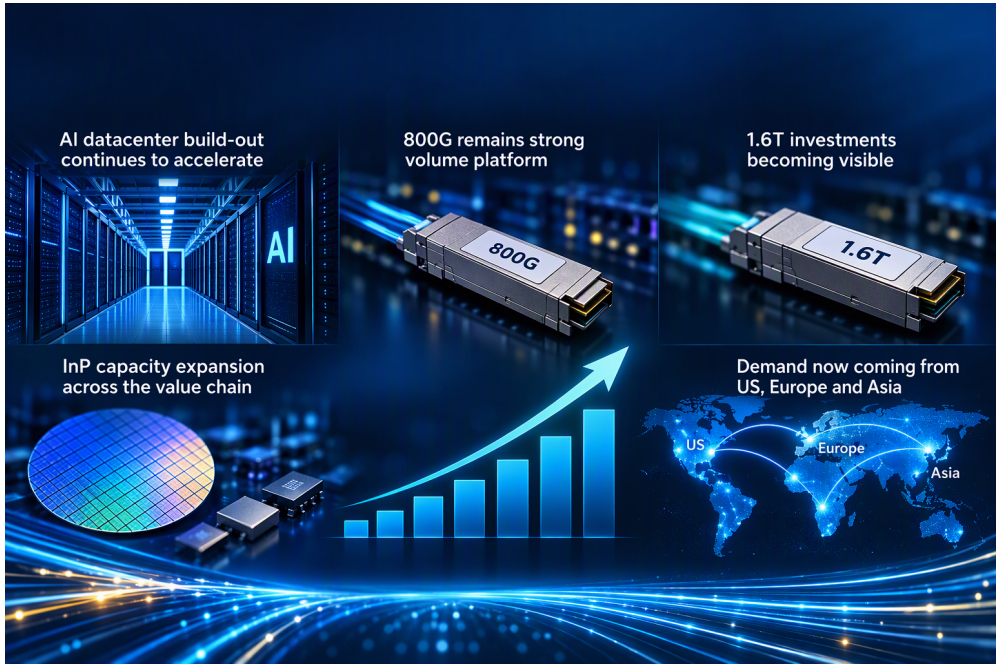
Layer	What It Means	Copper → Optics Transition
SCALE-UP	Connecting GPUs/XPUs within and across racks at full native speed (e.g., NVLink 5/6/7)	Today: 0% optics From 2027/2028: optics between GPUs/XPUs
SCALE-OUT	Connecting compute rack to other racks within the datacenters	Already using optics today (800G/1.6T transceivers). Growing with compute build-out
SCALE-ACROSS	Connecting data centers to each other and to the internet (coherent long-haul)	Upside scenario that can be accelerated with inference needs

Every expansion in AI compute requires a proportional increase in data interconnects, while changes in network architecture can drive non-linear growth in connectivity requirements.

Opto market is growing faster than expected

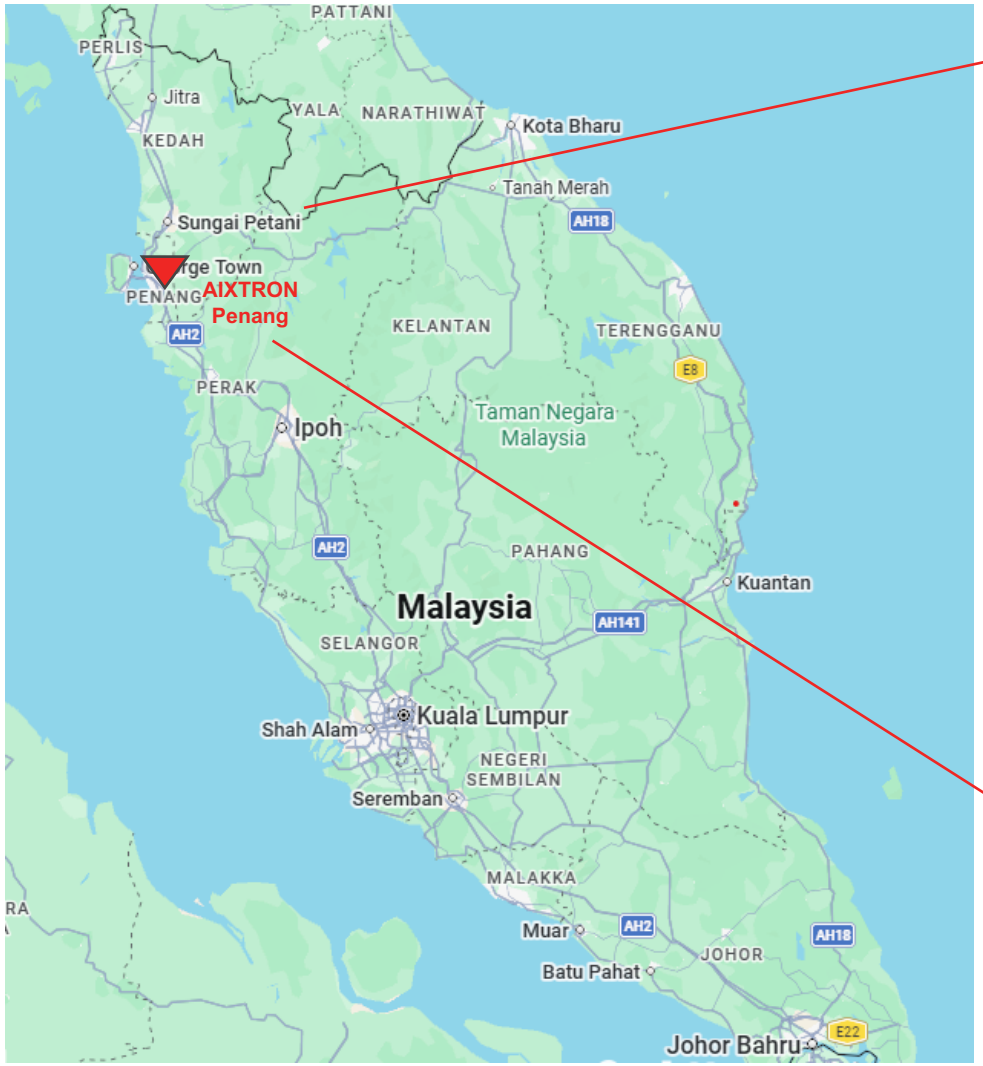
Why is the photonics market larger than previously expected?

- AI datacenter build-out continues to accelerate
- 800G remains strong volume platform
- 1.6T investments becoming visible
- Demand now coming from US, Europe and Asia
- Move to 6" InP wafers slower than expected



Market exceeds earlier tool expectations

New site in Malaysia – project fully on track



Strengthening long-term manufacturing flexibility and resilience

- Expansion of global production and supply chain footprint through a new facility in Penang, Malaysia
- Leverages Southeast Asia's strong semiconductor equipment ecosystem to support AIXTRON's growth
- Approx. EUR 40 million investment in 2026–2027
- Phased production ramp-up, with first system deliveries expected by end of 2027
- Adds approximately 25-30% manufacturing capacity by 2028
- Expansion potential beyond initial build-out if required

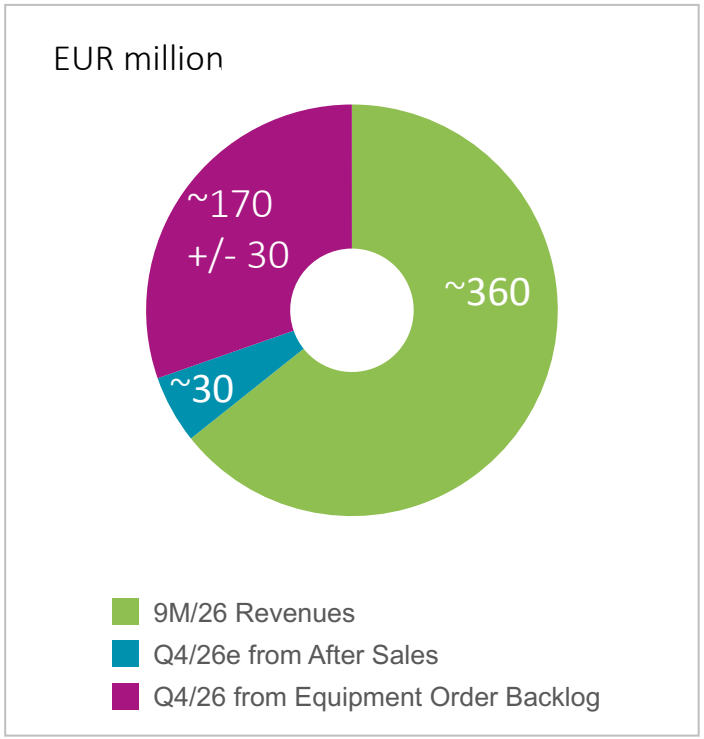
Q2/2026	Q3/2027	2028 onwards
Start of Construction ✓	***Start of Operations***	***Production, Engineering, Service***

Guidance for FY/2026

EUR million

Guidance[1]	FY/2026[1]
Revenues	EUR 560m ± 30m
Gross Margin (%)	around 42%
EBIT Margin (%)	17% to 20%

Revenue Guidance FY/2026



1: At $1.20/€ Budget Rate for 2026; please refer to the "Expected earnings and financial position" in the AIXTRON 2025 Annual Report

Our Financial Calendar:

04 Mar 2027	**FY/26 Results, Conference Call**
29 Apr 2027	**Q1/27 Results, Conference Call**
13 May 2027	**AGM for FY/26**

Conferences & Roadshows:

17 Nov	DZ Bank Equity Conf., FFM
18/19 Nov	MorganStanley TMT Conf., Barcelona
23 – 25 Nov	Eigenkapitalforum, FFM
30 Nov	Berenberg European Conf., London
2 Dec	UBS TMT Conf., Phoenix

For further information please contact:

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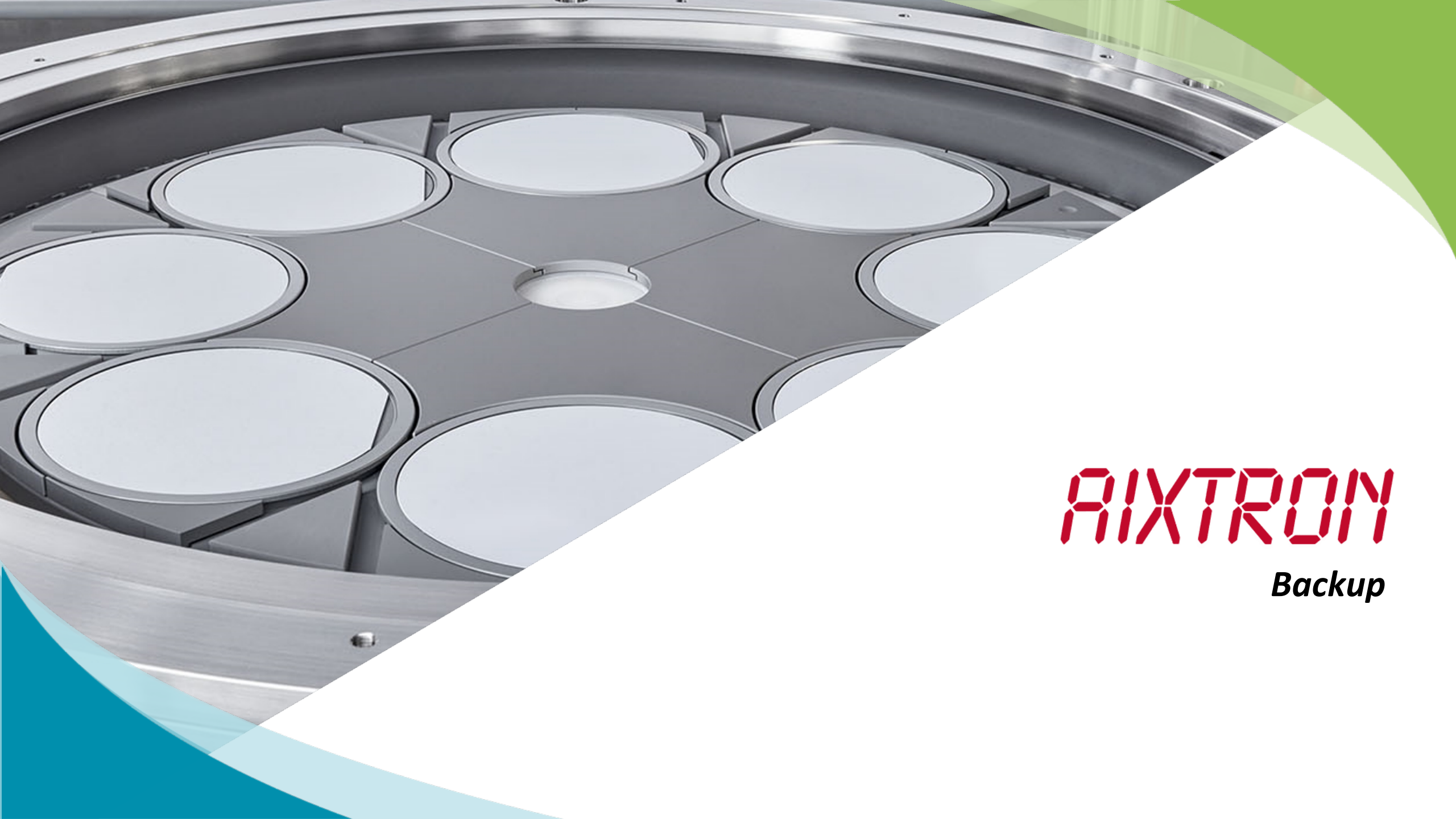
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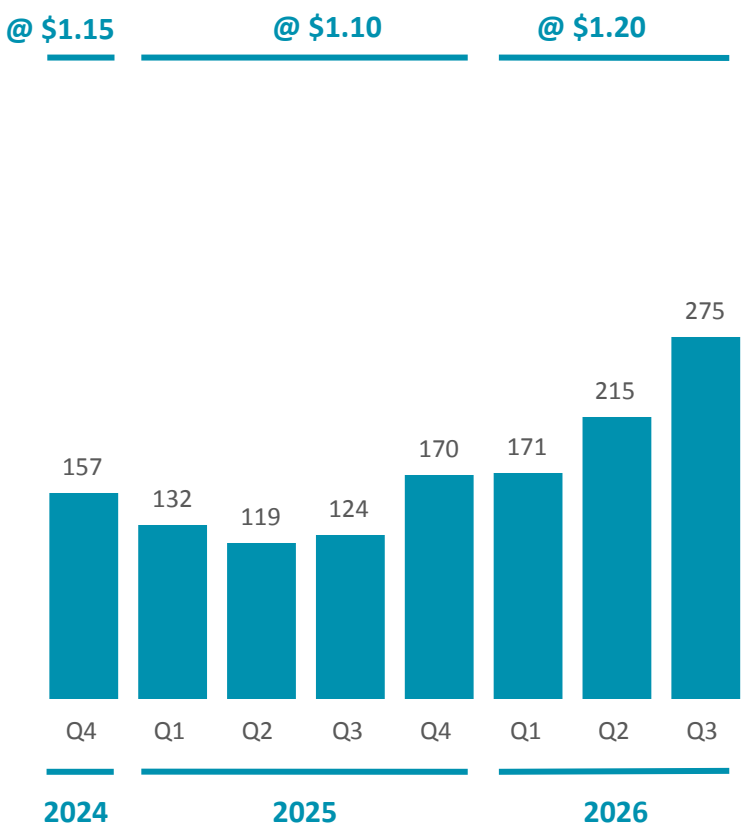
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Backup

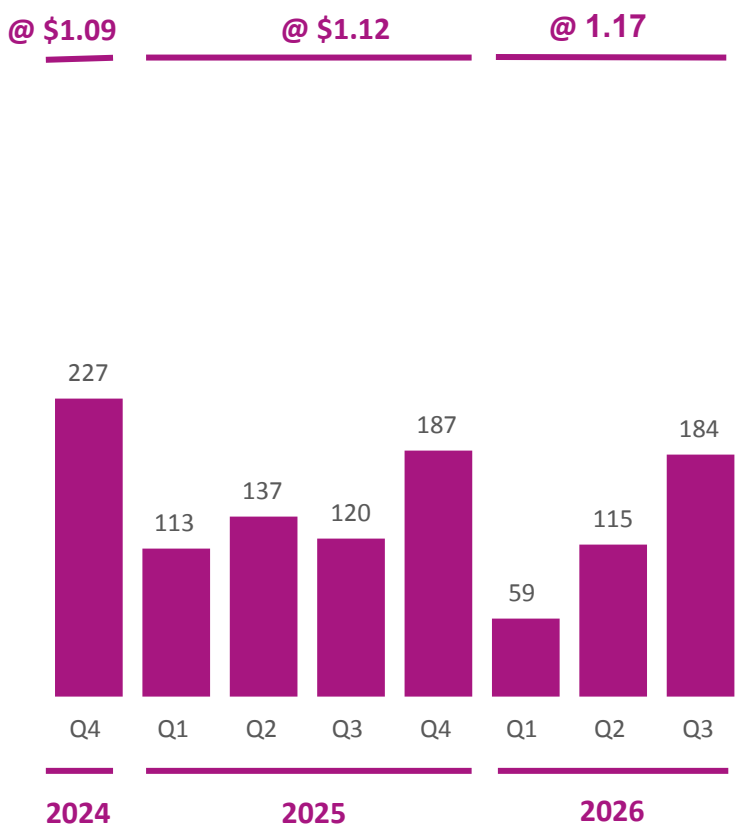
24 Months Business Development

EUR million

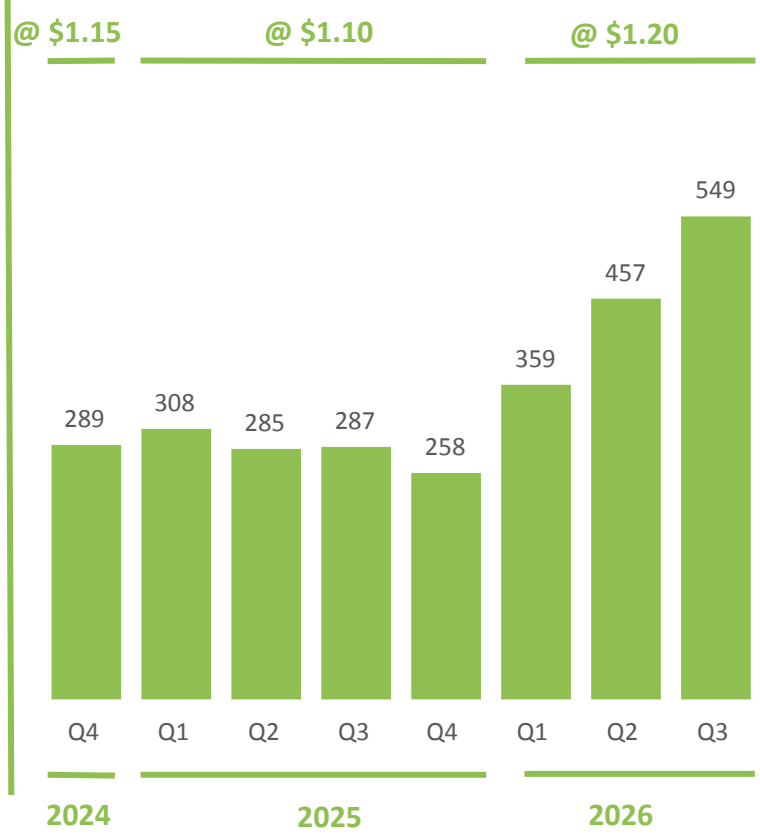
Order Intake
(incl. equipment & after sales)[1]



Revenues
(incl. equipment & after sales)[2]



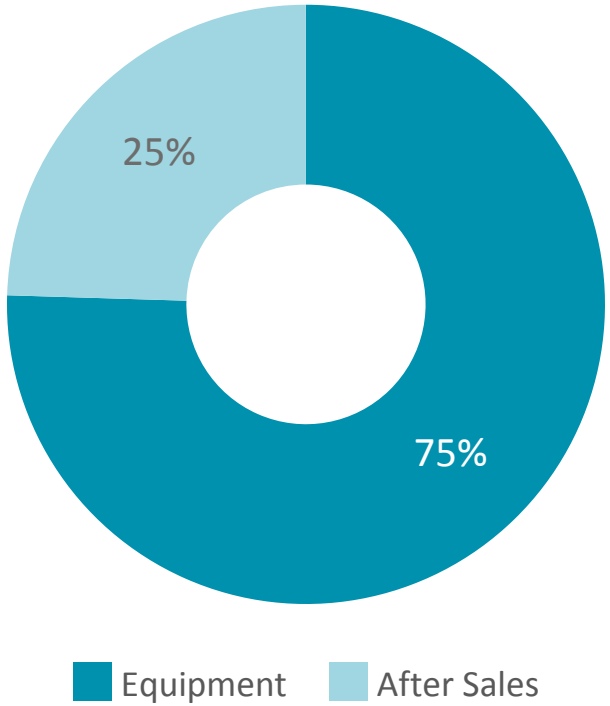
Order Backlog
(equipment only)[1]



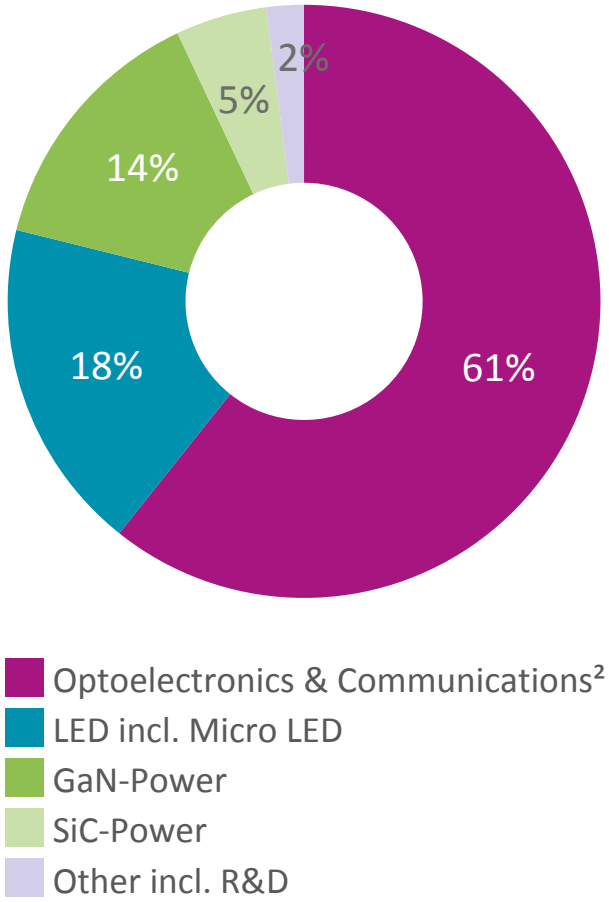
1 USD order intake and backlog were recorded at the prevailing budget rate (FY/2024: $1.15/€; 2025: $1.10/€)
2 USD revenues were converted at the actual period average FX rate (2024: $1.09/€; 2025: $1.12/€; 2026: $1.17/€)

9M/2026 Revenue Analysis[1]

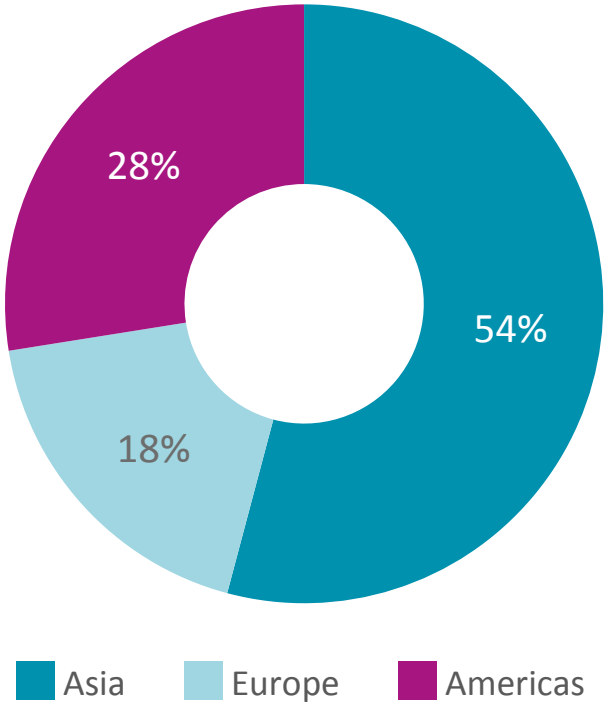
Equipment & After Sales



End Application (equipment only)



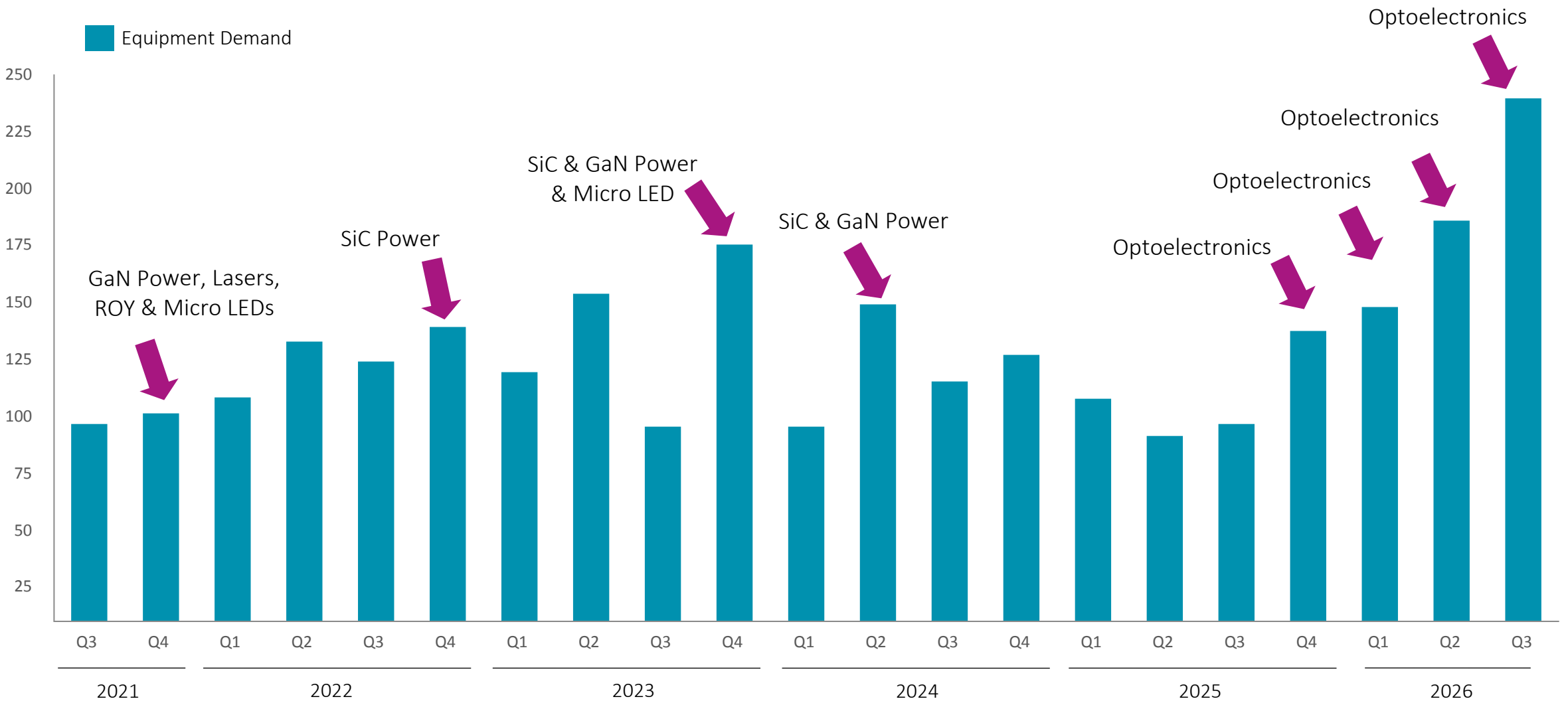
Regional Split



1 Rounded figures; may not add up
2 includes applications in Consumer Optoelectronics, Solar and Telecom/Datacom

Demand Drivers on Order Intake per Quarter (Equipment Only)

EUR million

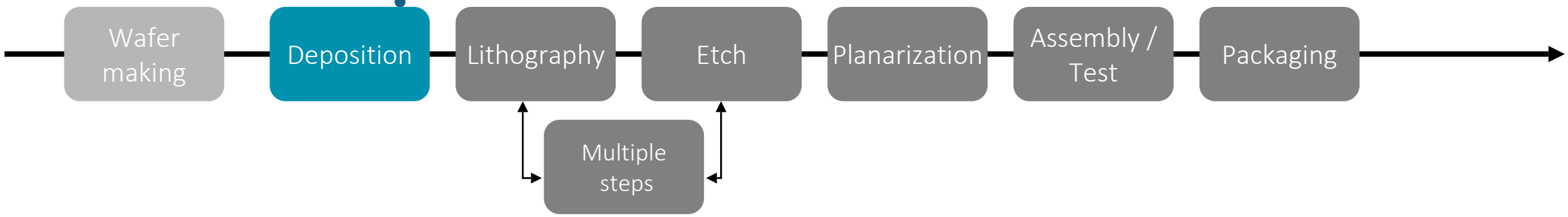


What We Do – deposition equipment for compound semiconductors



Focused Business Model

- AIXTRON is the leading supplier of **deposition equipment** to the **compound semiconductor industry**
- **(MO)CVD**: The tools run a **(Metal-Organic) Chemical Vapor Deposition** process for deposition of compound semiconductors
- Competitive strength comes from **strong focus** and clear **technology / market leadership** in **fast growing segments** of the market



Our growth is driven by megatrends that will continue through the cycle

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	1 SiC Power	2 GaN Power	3 Micro LED	4 Laser
Electrification of everything	✓	✓		
Energy efficiency	✓	✓		✓
AI and data		✓		✓
Digitization & communication		✓	✓	✓
IoT and intelligent devices		✓	✓	✓



G10-SiC



G10-GaN



G10-AsP

GaN power – acceleration of growth due to additional demand from AI

G10-GaN tool



Update

- AIXTRON maintains a **leading position in GaN power** segments
- 2026:
  - **Soft start into the year** as GaN adoption in broad range of applications is slower than expected
  - Co-existence of 200mm and 300mm wafer sizes expected, few customers moving to 300mm wafer size
- 2027:
  - **Increasing momentum** from fast growing low & mid voltage applications in **AI power delivery** (800V HVDC)
  - GaN penetrating more and more applications beyond AI, gradually replacing silicon (energy efficiency)

SiC power – positioned to outgrow the market through market-share gains

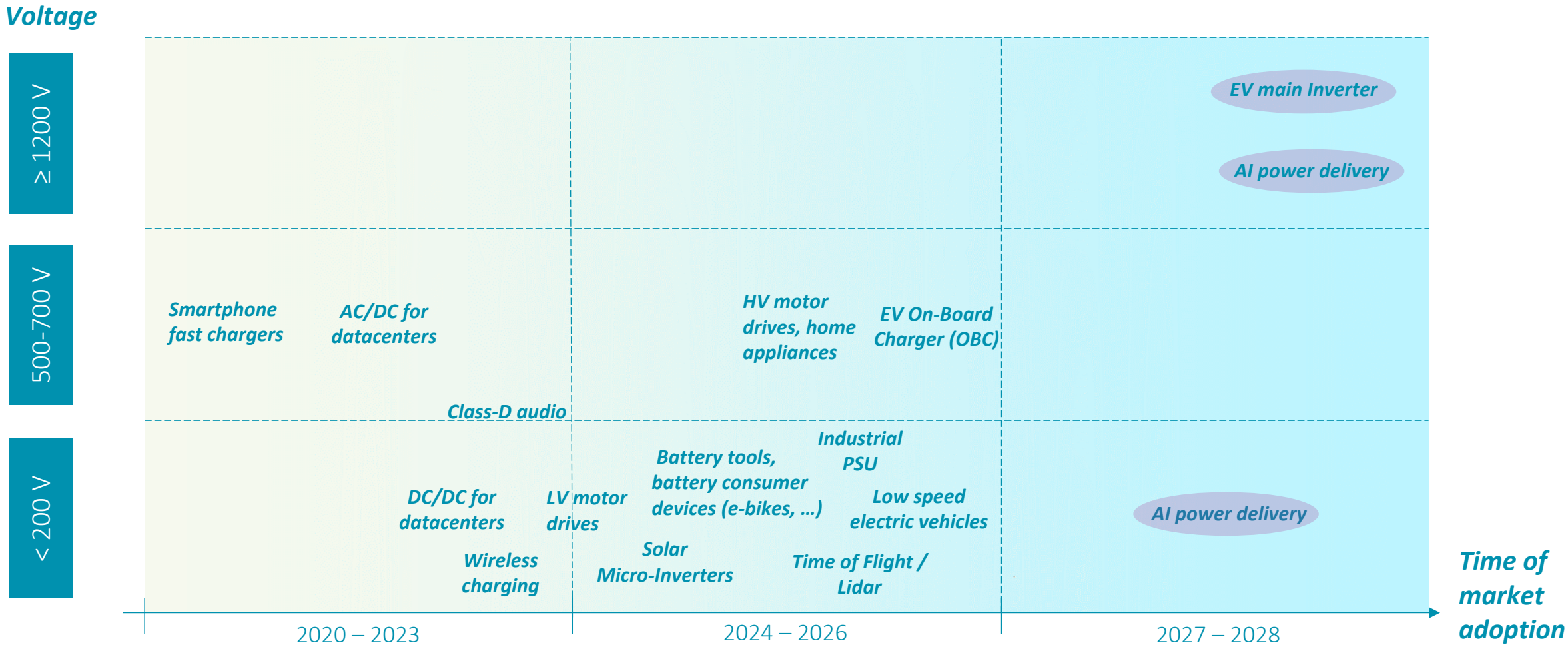
G10-SiC tool



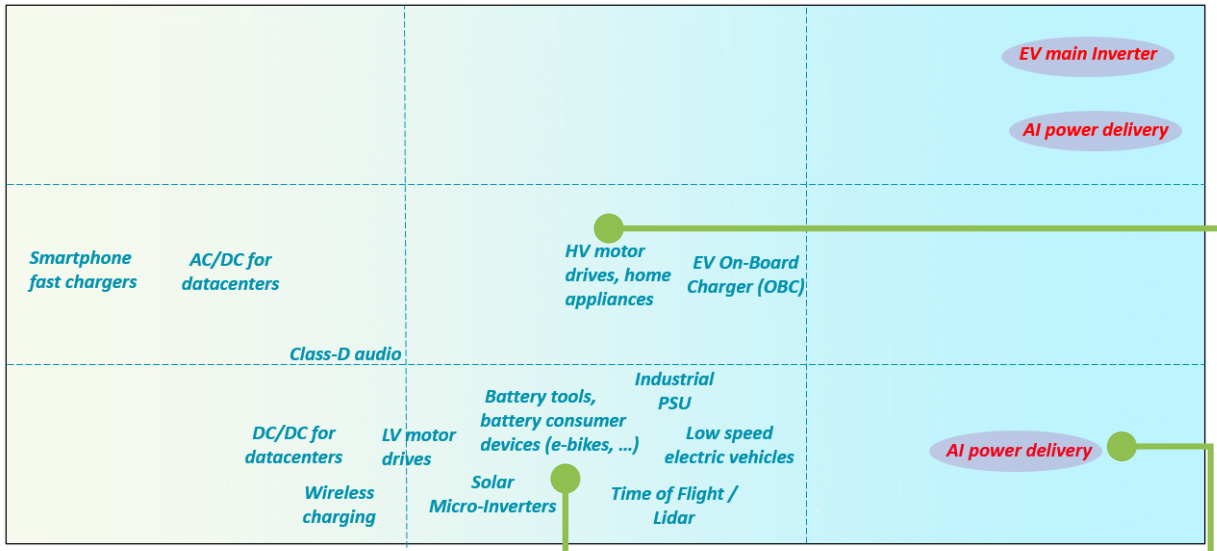
Update

- AIXTRON maintains a strong (leading) position in SiC power segments
- 2026:
  - Soft market for new tools but utilization increasing
- 2027-2028:
  - **New applications for SiC in "industrial" market**:
    - Highest voltage (2kV & 3kV) devices for grid-to-datacenter conversion
    - Solid-state-transformers (SSTs)
  - **Growing EV demand** for SiC devices as OEMs switch 400V to 800V battery systems
  - **Strong differentiation for AIXTRON G10-SiC** tool in upcoming technology trends "superjunction" and "highest voltage" devices

GaN power – growth is fueled by adding more and more applications



GaN power – selected case examples

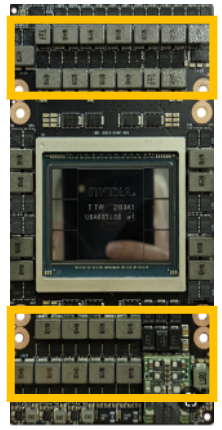


HV motor drives, home appliances



- Up to 40% energy consumption reduction
- Ramp from 2025 onwards
- High unit volume, large dies --> high wafer consumption

AI „On Board“ power delivery



- Replacement of silicon power chips around the GPUs
- Up to 50% lower power loss in a compact form factor

Battery tools and consumer devices

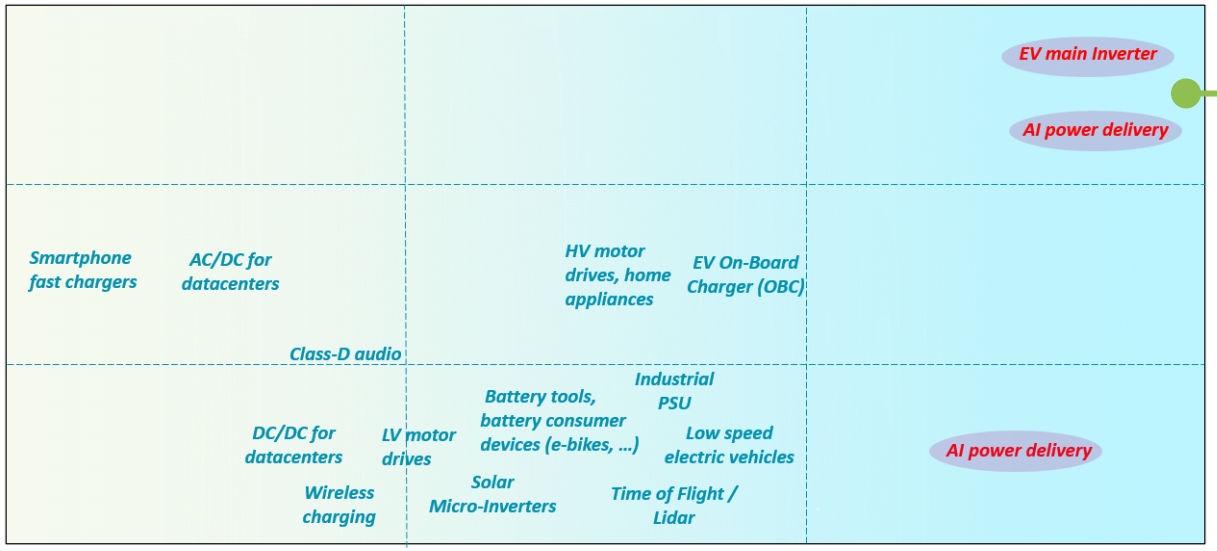




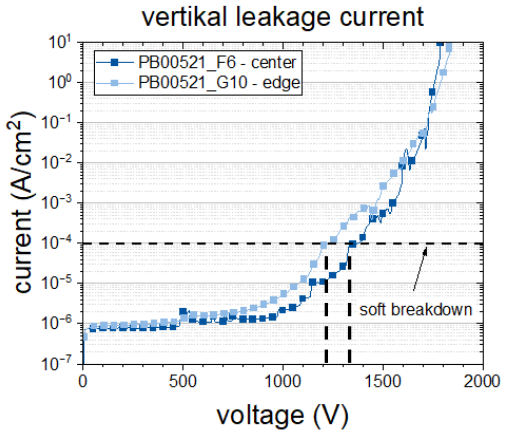
- Longer battery life
- Smaller size and reduced weight b/c less cooling

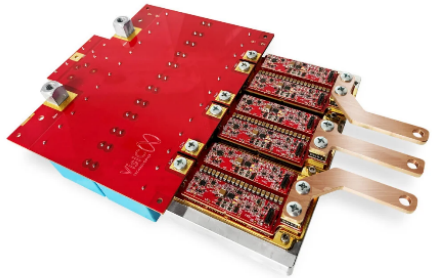
Design more efficient, compact motor systems with the DRV7308 GaN IPM | Video | TI.com

GaN power – selected case examples



GaN achieves > 1200V breakdown voltage





3-Phase traction inverter powered by GaN devices

Status of GaN for EV main inverters

- >= 1200V breakdown for GaN devices demonstrated, achieving key parameters required for HVM
- Multiple companies with 650V or 1200V prototypes in the roadmaps for traction inverters
- Potential for cost reduction in main inverter
- Test at several OEMs ongoing

Changan Automobile Launches First Commercial GaN-Based OBC Using Navitas Technology

February 6, 2025 Maurizio Di Paolo Emilio



Source: AIXTRON, measurement RWTH Aachen

GaN power – AIXTRON leads the market in 200mm today and is ready for 300mm ramp

200mm GaN multi-wafer tool



G10-GaN

- Leading platform for 150mm / 200mm wafer size
- Based on 20+ years GaN experience
- Used by all key GaN-players worldwide today (tool of record)

300mm GaN single-wafer tool



Hyperion

- Key ingredients from 200mm technology transferred to 300mm
- Builds on prior experience in GaN
  - Experience gained from today's installed base
  - 300mm showerhead technology (30+ years)
- Technological outperformance vs. 200mm platform recently confirmed by a leading customer

NVIDIA – HVDC Architecture combines SiC and GaN devices

NVIDIA 800 V HVDC Architecture will power the next generation of AI Factories



Key efficiency gains

- Up to 5% improvement in end-to-end power efficiency
- Maintenance costs reduced by up to 70% due to fewer PSU failures and lower labor costs for component upkeep
- Lower cooling expenses from eliminating AC/DC PSUs inside IT racks

Source: NVIDIA

Navitas developing next generation 800V HVDC architecture with NVIDIA

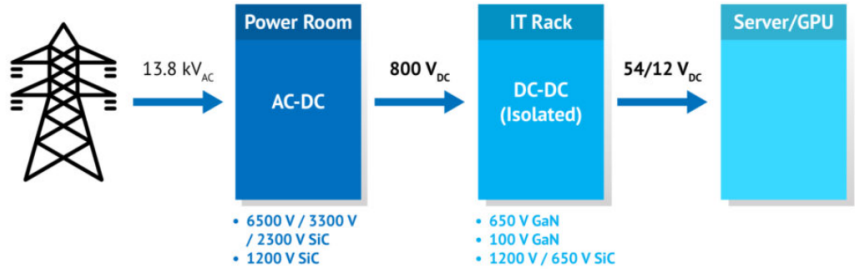
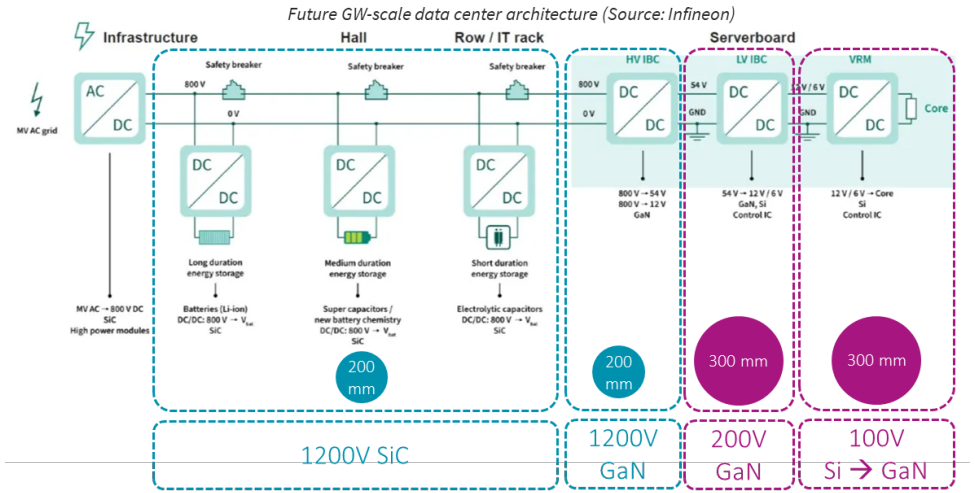


Fig. 1. Navitas GaN and SiC technologies cover the complete power delivery from grid to the GPU.

Source: Navitas

Next-Generation Power Architecture (NVIDIA & Infineon)



Source: Powerelectronicsnews + Infineon

Micro LED / LED – development and pilot activities continue



G10-AsP



G5+

Update

- **Continued work in Asia** on LED brightness and cost per display
- **ROY LEDs:** China dominates market;
  - **local consolidation** drives vertical partnerships (e.g. with panel makers)
- **Micro LED**: Still early-stage;
  - secured orders are targeting the **exploration of the potential of the product**,
  - but **cost-effective production still remains the biggest challenge** for high volume manufacturing

Renewed product portfolio – strong market adoption of G10 tool family

G10-SiC



- 9x150mm (6“) or 6x200mm (8“)
- Cost benefit of batch tool with uniformity on par with single wafer tool
- Highest productivity in the market

- **End Markets/Products:** Electric vehicles, charging infrastructure

G10-GaN



- 8x150mm (6“) or 5x200mm (8“)
- Compact cluster for high volume GaN manufacturing
- Designed for replacement of Si power devices with GaN devices

- **End Markets/Products:** GaN Power Electronics & Wireless communication

G10-AsP



- 12x100mm (4“) or 8x150mm (6“)
- Fully automated AsP MOCVD system
- 10x lower defect density than predecessor tool

- **End Markets/Products:** Micro LED, Optical Communications, 3D-sensing & LiDAR

All G10 models now well established; G10-AsP gaining momentum in laser market

AIXTRON Competitive Landscape – clear market leader

		USA	Europe	China/Taiwan	Japan
Opto	GaAs/InP Lasers ROY (Micro) LED	Veeco		NAURA 北方华创, 中晟, AMEC	
	GaN (Micro) LED	Veeco		NAURA 北方华创, 中晟, AMEC	
Power	GaN Power	Veeco		NAURA 北方华创, 中晟, AMEC	
	SiC Power		ASM	NAURA 北方华创, JSG, CETC	NuFlare

Source: AIXTRON market research

Consolidated Income Statement[1]

(EUR million)	9M/2026	9M/2025	+/- (%)	Q3/2026	Q3/2025	+/- (%)
Revenues	**358.1**	**369.5**	**-3**	**183.6**	**119.6**	**54**
Cost of sales	213.2	233.2	-9	96.3	73.2	32
Gross profit	**144.9**	**136.2**	**6**	**87.3**	**46.4**	**88**
Gross margin	*40%*	*37%*	*3pp*	*48%*	*39%*	*9pp*
Selling expenses	13.9	13.0	7	4.4	3.9	13
General & admin expenses	26.4	24.2	9	9.7	7.7	26
R&D	69.8	59.7	17	22.8	23.7	-4
Net other operating expenses (income)	(14.3)	(3.0)	>300	(6.3)	(4.3)	47
EBIT	**49.1**	**42.3**	**16**	**56.7**	**15.4**	**268**
EBIT margin	*14%*	*11%*	*3pp*	*31%*	*13%*	*18pp*
Net profit	**32.6**	**37.3**	**-13**	**35.4**	**13.0**	**172**

- 9M/2026 Gross Profit & EBIT impacted by one-off expenses in the mid-single-digit EUR million range related to the personnel reduction implemented in the operations area

1 Rounded figures; may not add up

Consolidated Balance Sheet[1]

(EUR million)	30.09.26	30.06.26	31.12.25
Property, plant & equipment and leased assets	242.4	238.8	241.9
Goodwill	72.2	72.0	71.6
Other intangible assets	8.1	5.8	6.1
Others	28.2	41.5	36.3
Non-current assets	**350.8**	**358.2**	**355.8**
Inventories	323.3	317.9	283.6
Trade receivables	110.2	81.0	130.7
Others	60.8	63.4	45.1
Cash & cash deposits & investments	944.8	816.2	224.6
Current assets	**1,439.1**	**1,278.4**	**684.0**
Equity	**1,030.8**	**992.7**	**910.4**
Non-current liabilities	**360.9**	**355.5**	**7.4**
Trade payables	40.8	49.2	33.6
Contract liabilities for advance payment	309.0	197.5	44.5
Others	48.4	41.6	43.9
Current liabilities	**398.3**	**288.3**	**121.9**
Balance sheet total	**1,790.0**	**1,636.6**	**1,039.8**

1 Rounded figures; may not add up

Consolidated Statement of Cash Flows[1]

(EUR million)	9M/2026	9M/2025	Q3/2026	Q3/2025
Net result	**32.6**	**37.3**	**35.4**	**13.0**
Adjust for:				
Non-cash items & others	24.9	-8.3	35.5	-4.1
Changes in Working Capital[2]	253.6	99.5	67.6	34.5
Cash flow from operating activities	**311.1**	**128.5**	**138.4**	**43.4**
Capital expenditures/disposals	-21.2	-18.2	-10.6	-4.2
Free cash flow	**289.9**	**110.3**	**127.8**	**39.2**
FX effects/other	3.0	-4.0	1.8	-0.5
Cash & cash deposits & investments	**944.8**	**153.4**	**944.8**	**153.4**

1 Rounded figures; may not add up
2 Working Capital = Inventories + Trade Receivables - Trade Payables - Contract Liabilities for Advance Payments; excl. FX-effects; updated definition applied to all periods

Four Year View on Consolidated Income Statement[1]

(EUR million)	FY/25	FY/24	FY/23	FY/22
Revenues	**556.6**	**633.2**	**629.9**	**463.2**
Cost of sales	334.2	370.7	350.8	267.9
Gross profit	**222.4**	**262.5**	**279.0**	**195.3**
Gross margin	*40%*	*41%*	*44%*	*42%*
Selling expenses	16.3	14.2	14.1	11.2
General & admin expenses	32.1	31.9	32.6	29.2
R&D	81.1	91.4	87.7	57.7
Net other operating expenses (income)	(7.5)	(6.2)	(12.1)	(7.6)
EBIT	**100.3**	**131.2**	**156.8**	**104.7**
EBIT margin	*18%*	*21%*	*25%*	*23%*
Net result	**85.3**	**106.2**	**145.2**	**100.5**

1 Rounded figures; may not add up

Four Year View on Consolidated Balance Sheet[1]

(EUR million)	31.12.2025	31.12.2024	31.12.2023	31.12.2022
Property, plant & equipment and leased assets	241.9	226.9	147.8	99.0
Goodwill	71.6	73.5	72.3	72.5
Other intangible assets	6.1	7.4	4.4	3.3
Others	36.3	39.2	41.8	34.9
Non-current assets	**355.8**	**347.1**	**266.3**	**209.7**
Inventories	283.6	369.1	394.5	223.6
Trade receivables	130.7	193.4	157.6	119.7
Others	45.1	44.2	30.0	24.5
Cash & cash deposits & investments	224.6	64.6	181.7	325.2
Current Assets	**684.0**	**671.3**	**763.7**	**692.9**
Equity	**910.4**	**848.0**	**777.6**	**663.3**
Non-current liabilities	**7.4**	**7.5**	**7.7**	**10.0**
Trade payables	33.6	33.9	57.8	46.1
Contract liabilities for advance payment	44.5	81.7	141.3	141.2
Others	43.9	47.3	45.6	41.9
Current liabilities	**121.9**	**162.9**	**244.6**	**229.3**
Balance Sheet total	**1,039.8**	**1,018.4**	**1,029.9**	**902.6**

1 Rounded figures; may not add up

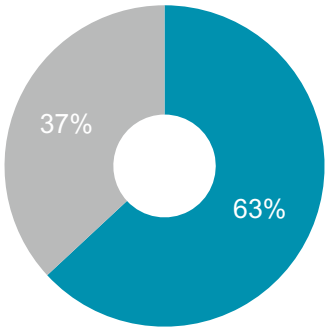
Four Year View on Consolidated Statement of Cash Flows[1]

(EUR million)	FY/25	FY/24	FY/23	FY/22
Net Result	**85.3**	**106.2**	**145.2**	**100.5**
Adjust for:				
Non-Cash Items & others	14.4	9.1	4.3	-11.9
Changes in Working Capital[2]	108.7	-89.1	-196.8	-51.5
Cash Flow from Operating Activities[2]	**208.4**	**26.2**	**-47.3**	**37.1**
Capital Expenditures/Disposals	-26.4	-98.6	-62.4	-29.5
Free Cash Flow	**181.9**	**-72.4**	**-109.7**	**7.7**
FX Effects/Other	-4.8	1.3	-1.7	-0.4
Cash & cash deposits & investments	**224.6**	**64.6**	**181.7**	**325.2**

1 Rounded figures; may not add up
2 Working Capital = Inventories + Trade Receivables - Trade Payables - Contract Liabilities for Advance Payments; excl. FX-effects; updated definition applied to all periods

EU Taxonomy Alignment & ESG-Ratings

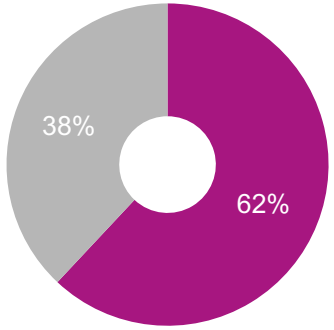
FY/2025: Revenues[1]



Taxonomy Aligned

Taxonomy Non-Aligned

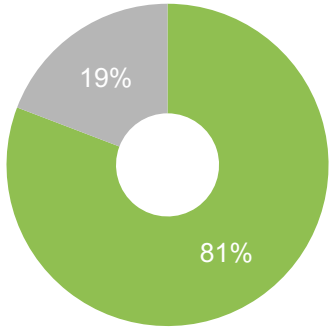
FY/2025: CapEx[1]



Taxonomy Aligned

Taxonomy Non-Aligned

FY/2025: OpEx[1]



Taxonomy Aligned

Taxonomy Non-Aligned

[1] In line with EU Taxonomy Regulation

EU Taxonomy Aligned Technologies

- **Wide Band Gap (WBG) Power Semiconductors** based on:
  - **Gallium Nitride (GaN) and**
  - **Silicon Carbide (SiC)**

  Key technologies for energy-efficient Power Electronics
- **Micro LEDs:**
  For the next generation of displays
- **Laser Diodes for Data Communication:**
  Key technology for the digitalization of our world
- **Photovoltaics based on Compound Semiconductors:**
  For high-tech applications (e.g.,space applications)
- **Quantum Technologies:**
  For neuromorphic computing and quantum sensing

ESG-Ratings

- **CDP (Europe):**
  - 2025: C
  - 2024: C
- **MSCI:**
  - 2025: AA
  - 2024: AA
- **Sustainalytics:**
  - 2025: 18.1 - Low risk
  - 2024: 20.8 - Medium risk
- **ISS Oekom:**
  - 2025: C
  - 2024: C



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